

# 2N4401

Preferred Device

## General Purpose Transistors

### NPN Silicon

#### Features

- Pb-Free Packages are Available\*

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	$V_{CEO}$	40	Vdc
Collector – Base Voltage	$V_{CBO}$	60	Vdc
Emitter – Base Voltage	$V_{EBO}$	6.0	Vdc
Collector Current – Continuous	$I_C$	600	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

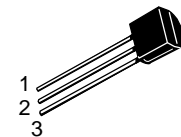
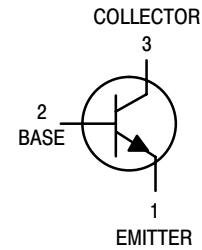
#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$



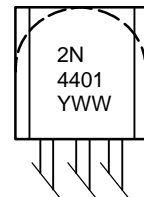
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<http://onsemi.com>



TO-92  
CASE 29  
STYLE 1

#### MARKING DIAGRAM



Y = Year  
WW = Work Week

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# 2N4401

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
<b>OFF CHARACTERISTICS</b>					
Collector–Emitter Breakdown Voltage (Note 1) ( $I_C = 1.0\text{ mAdc}$ , $I_B = 0$ )	$V_{(BR)CEO}$	40	–	Vdc	
Collector–Base Breakdown Voltage ( $I_C = 0.1\text{ mAdc}$ , $I_E = 0$ )	$V_{(BR)CBO}$	60	–	Vdc	
Emitter–Base Breakdown Voltage ( $I_E = 0.1\text{ mAdc}$ , $I_C = 0$ )	$V_{(BR)EBO}$	6.0	–	Vdc	
Base Cutoff Current ( $V_{CE} = 35\text{ Vdc}$ , $V_{EB} = 0.4\text{ Vdc}$ )	$I_{BEV}$	–	0.1	$\mu\text{A}$ dc	
Collector Cutoff Current ( $V_{CE} = 35\text{ Vdc}$ , $V_{EB} = 0.4\text{ Vdc}$ )	$I_{CEX}$	–	0.1	$\mu\text{A}$ dc	
<b>ON CHARACTERISTICS (Note 1)</b>					
DC Current Gain ( $I_C = 0.1\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 10\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 150\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 500\text{ mAdc}$ , $V_{CE} = 2.0\text{ Vdc}$ )	$h_{FE}$	20 40 80 100 40	– – – 300 –	–	
Collector–Emitter Saturation Voltage ( $I_C = 150\text{ mAdc}$ , $I_B = 15\text{ mAdc}$ ) ( $I_C = 500\text{ mAdc}$ , $I_B = 50\text{ mAdc}$ )	$V_{CE(sat)}$	– –	0.4 0.75	Vdc	
Base–Emitter Saturation Voltage ( $I_C = 150\text{ mAdc}$ , $I_B = 15\text{ mAdc}$ ) ( $I_C = 500\text{ mAdc}$ , $I_B = 50\text{ mAdc}$ )	$V_{BE(sat)}$	0.75 –	0.95 1.2	Vdc	
<b>SMALL–SIGNAL CHARACTERISTICS</b>					
Current–Gain – Bandwidth Product ( $I_C = 20\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 100\text{ MHz}$ )	$f_T$	250	–	MHz	
Collector–Base Capacitance ( $V_{CB} = 5.0\text{ Vdc}$ , $I_E = 0$ , $f = 1.0\text{ MHz}$ )	$C_{cb}$	–	6.5	pF	
Emitter–Base Capacitance ( $V_{EB} = 0.5\text{ Vdc}$ , $I_C = 0$ , $f = 1.0\text{ MHz}$ )	$C_{eb}$	–	30	pF	
Input Impedance ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{ie}$	1.0	15	k ohms	
Voltage Feedback Ratio ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{re}$	0.1	8.0	$\times 10^{-4}$	
Small–Signal Current Gain ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{fe}$	40	500	–	
Output Admittance ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{oe}$	1.0	30	$\mu\text{mhos}$	
<b>SWITCHING CHARACTERISTICS</b>					
Delay Time	$(V_{CC} = 30\text{ Vdc}$ , $V_{BE} = 2.0\text{ Vdc}$ , $I_C = 150\text{ mAdc}$ , $I_{B1} = 15\text{ mAdc}$ )	$t_d$	–	15	ns
Rise Time		$t_r$	–	20	ns
Storage Time	$(V_{CC} = 30\text{ Vdc}$ , $I_C = 150\text{ mAdc}$ , $I_{B1} = I_{B2} = 15\text{ mAdc}$ )	$t_s$	–	225	ns
Fall Time		$t_f$	–	30	ns

1. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

ORDERING INFORMATION

Device	Package	Shipping†
2N4401	TO-92	5,000 Units / Box
2N4401RLRA	TO-92	2,000 / Tape & Reel
2N4401RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Reel
2N4401RLRM	TO-92	2,000 / Ammo Pack
2N4401RLRP	TO-92	2,000 / Ammo Pack
2N4401RLRPG	TO-92 (Pb-Free)	2,000 / Ammo Pack
2N4401ZL1	TO-92	2,000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

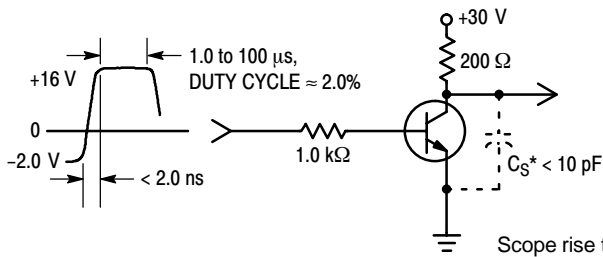


Figure 1. Turn-On Time

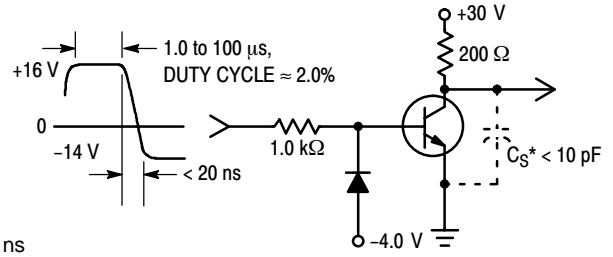


Figure 2. Turn-Off Time

TRANSIENT CHARACTERISTICS

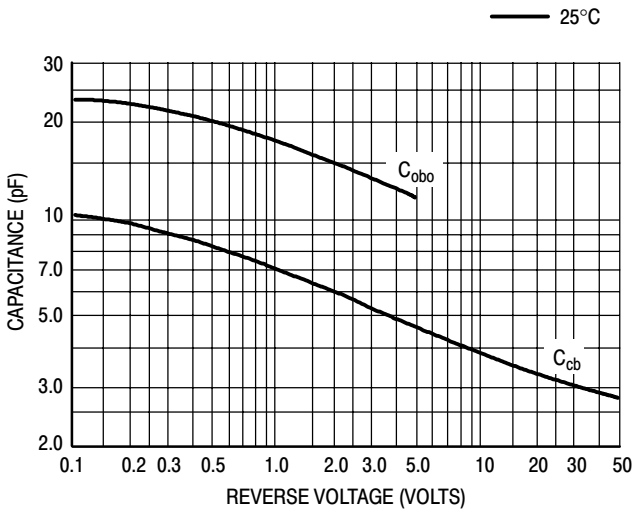


Figure 3. Capacitances

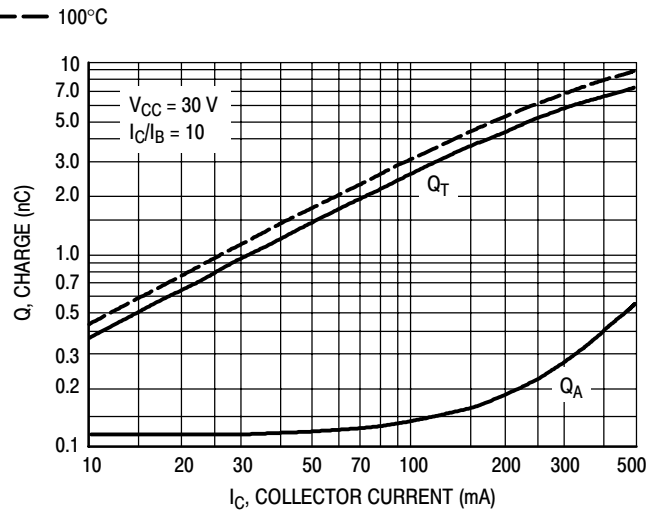


Figure 4. Charge Data

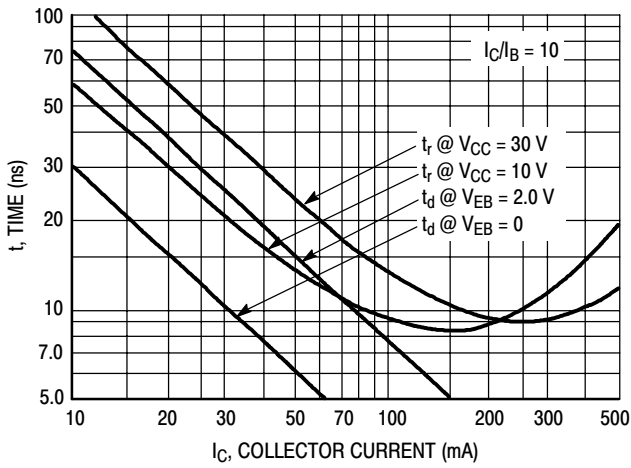


Figure 5. Turn-On Time

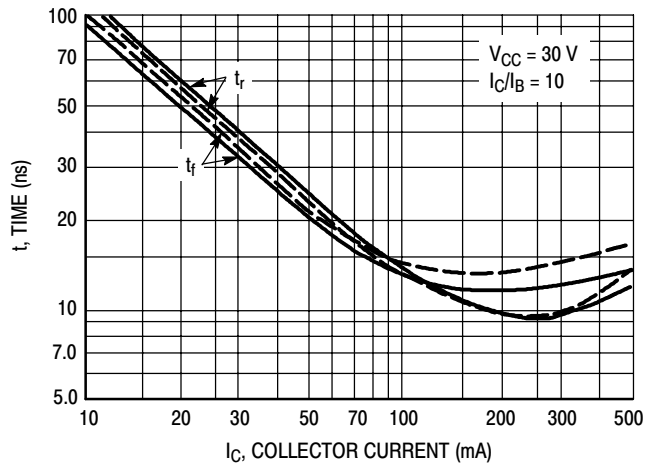


Figure 6. Rise and Fall Times

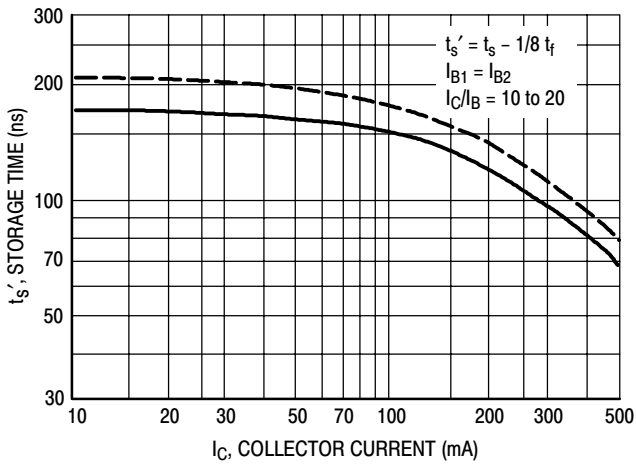


Figure 7. Storage Time

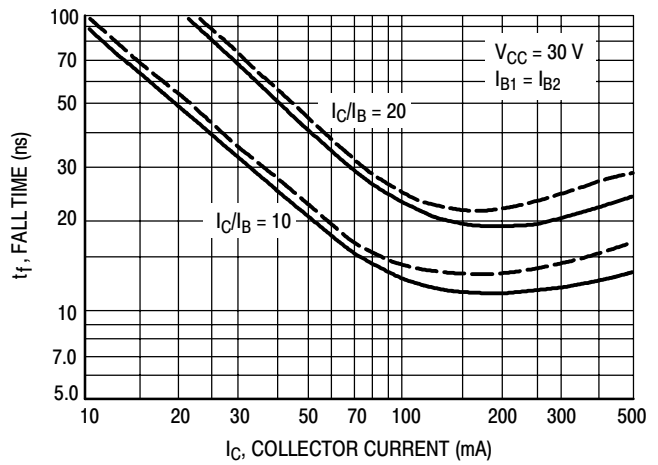


Figure 8. Fall Time

SMALL-SIGNAL CHARACTERISTICS

NOISE FIGURE

$V_{CE} = 10 \text{ Vdc}$ ,  $T_A = 25^\circ\text{C}$ ; Bandwidth = 1.0 Hz

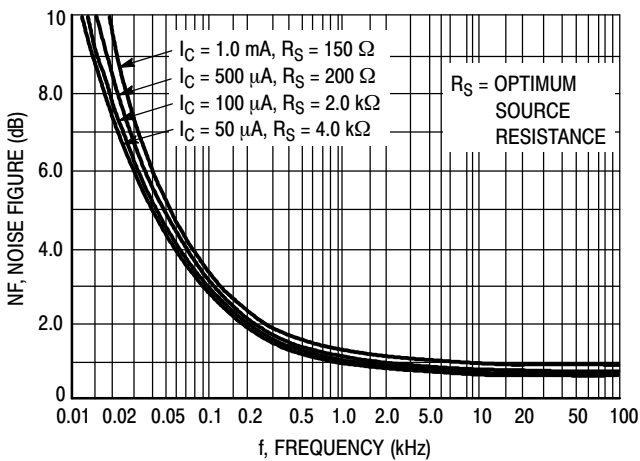


Figure 9. Frequency Effects

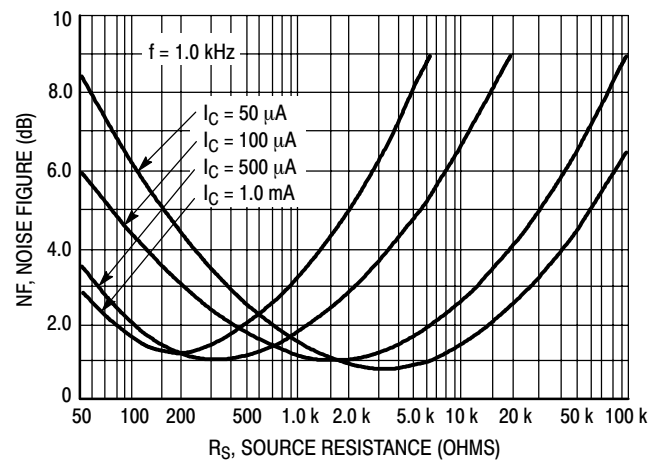


Figure 10. Source Resistance Effects

# 2N4401

## h PARAMETERS

$V_{CE} = 10 \text{ Vdc}$ ,  $f = 1.0 \text{ kHz}$ ,  $T_A = 25^\circ\text{C}$

This group of graphs illustrates the relationship between  $h_{fe}$  and other "h" parameters for this series of transistors. To obtain these curves, a high-gain and a low-gain unit were

selected from the 2N4401 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

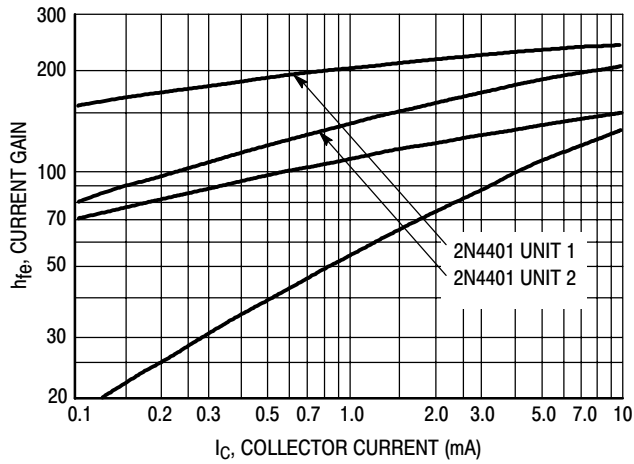


Figure 11. Current Gain

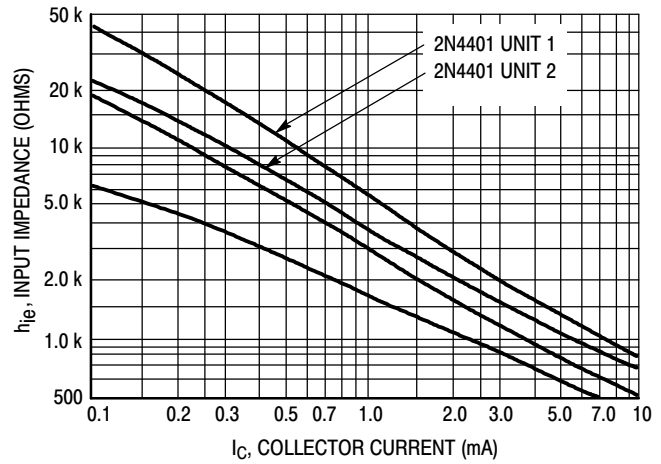


Figure 12. Input Impedance

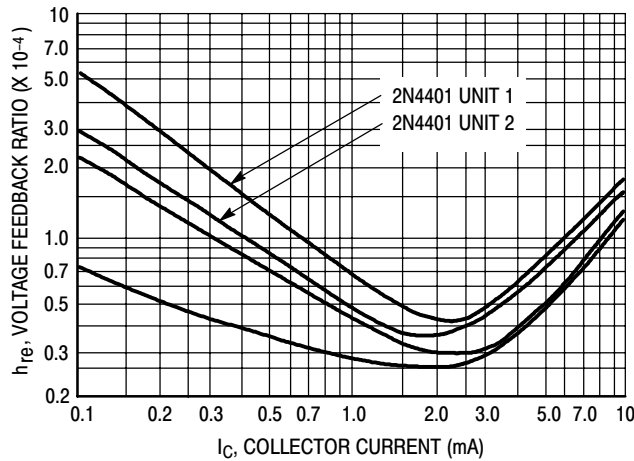


Figure 13. Voltage Feedback Ratio

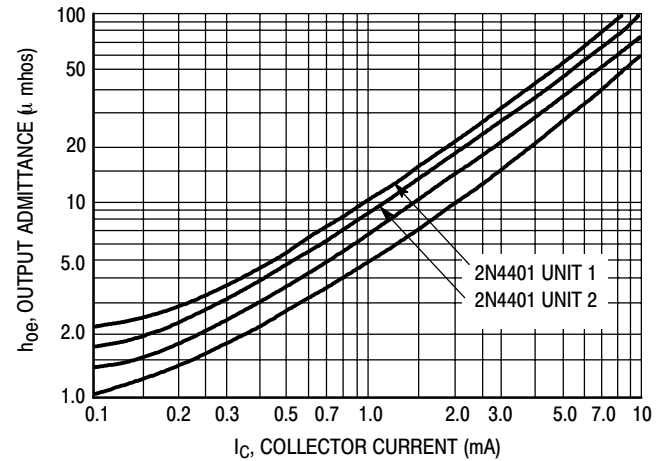


Figure 14. Output Admittance

# 2N4401

## STATIC CHARACTERISTICS

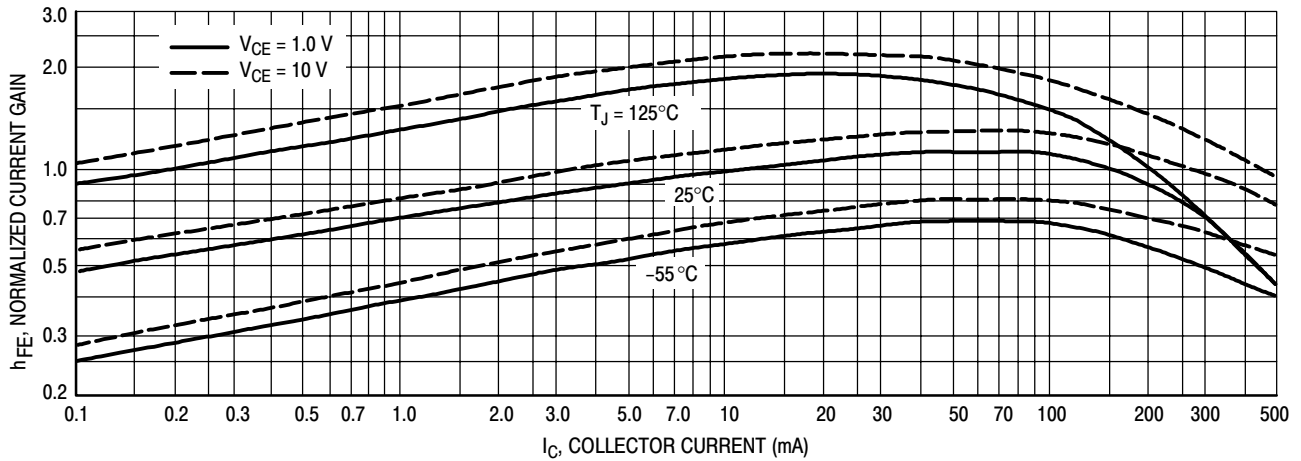


Figure 15. DC Current Gain

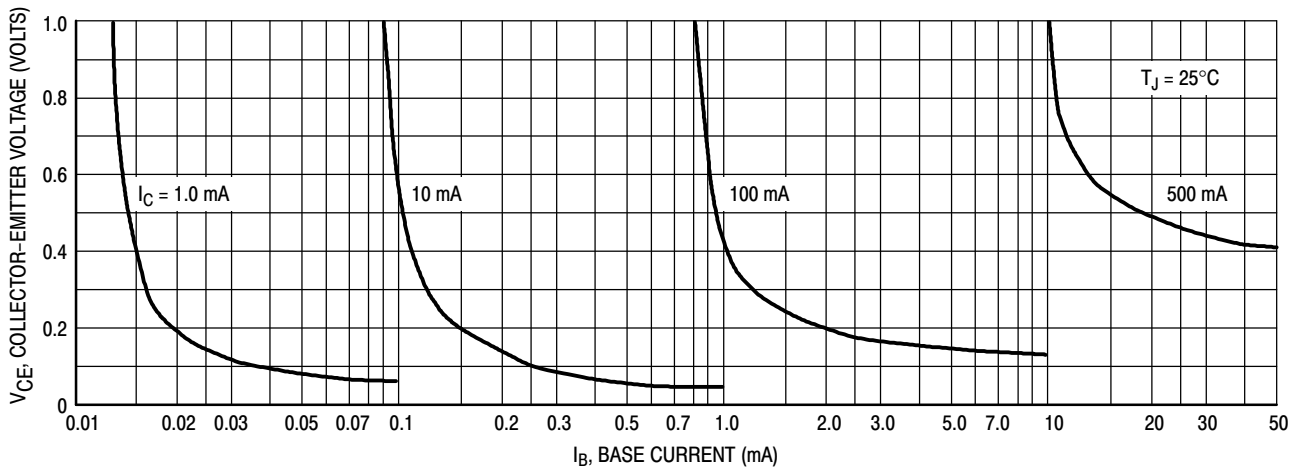


Figure 16. Collector Saturation Region

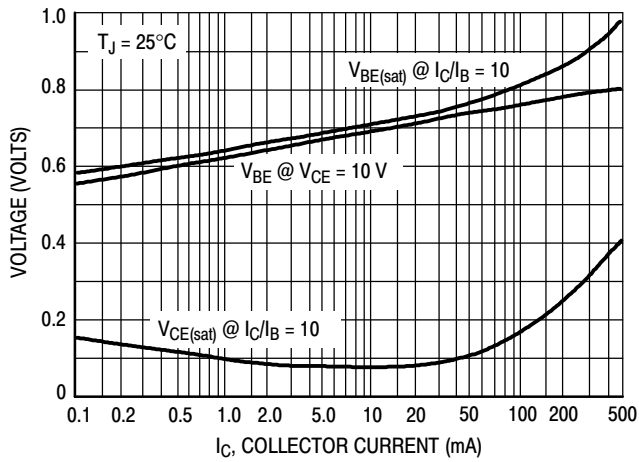


Figure 17. "On" Voltages

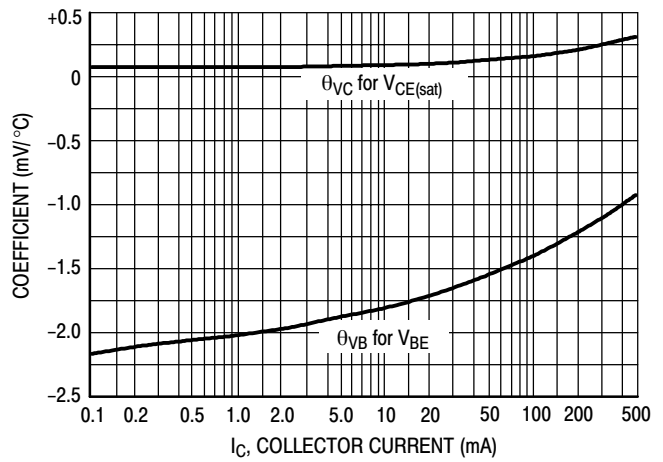
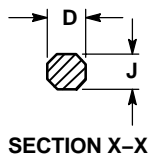
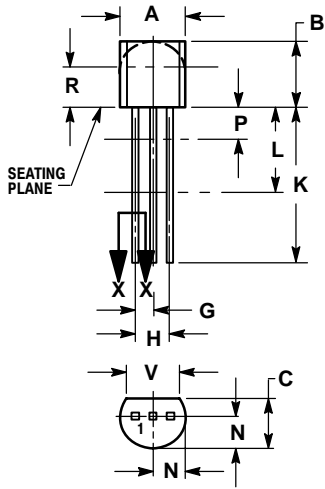


Figure 18. Temperature Coefficients

# 2N4401

## PACKAGE DIMENSIONS

TO-92  
TO-226AA  
CASE 29-11  
ISSUE AL




**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

**STYLE 1:**

- PIN 1. EMITTER
2. BASE
3. COLLECTOR

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